FEATURES

- Rated current of 20A, rated voltage of 60VDC, and rated breaking current of 100A achieved in spite of its compact size of 3.2x1.6x1.4mm by our original structure.
- 2. Fast-acting type fuse with little variation in fusing characteristics.
- 3. Performance against rush current is excellent since plate material is used for fuse element.
- Surface temperature rise is 75°C or less when applying rated current for fusing. This gives less influence to the peripheral units.
- 5. Resistance to soldering heat: Reflow or flow soldering 10 seconds at 260 °C.
- 6. Our original terminal construction makes almost no occurrence of Tombstone phenomenon.
- 7. Suitable for automatic mounting
- 8. Precise dimensions allows high-density mounting and symmetrical construction of terminals provide "Self-Alignment".
- 9. Complete lead-free, bromine-free.



DERATING (REFERENCE DATA)

99 mV

Steady current flowing through the fuse must be reduced by the ambient temperature.



83 mV



FUSING CHARACTERISTICS

Туре	Current (rated current standard)	Time		
Type JAJ	100 %	Not fusing more than 1 hour		
	200 %	Fusing within 1 minute		
Type JAK	100 %	Not fusing more than 1 hour		
	250 %	Fusing within 1 minute		

FUSING CHARACTERISTICS (REFERENCE DATA)



MARKING

Code	Type JAJ Rated Current	Type JAK Rated Current
Ψ.	12.5 A	10 A
х.	16 A	12.5 A
Ζ.		16 A
Υ.		20 A

Fusing Characteristics

CATALOG NUMBERS AND RATING

Type JAJ	(200% fused product)	

Marking Code	Catalog number	Rated current	Resistance (Reference)
w.	JAJ 6002133 NA52	12.5 A	4.59 mΩ
х.	JAJ 6002163 NA52	16 A	3.60 mΩ

Type JAK (250% fused product)

Marking Code	Catalog number	Rated current	Resistance (Reference)
w.	JAK 6002103 NA52	10 A	4.59 mΩ
х.	JAK 6002133 NA52	12.5 A	3.60 mΩ
Ζ.	JAK 6002163 NA52	16 A	2.93 mΩ
Υ.	JAK 6002203 NA52	20 A	2.40 mΩ

Type JAJ and type JAK with the same rating marking code have exactly the same dimension, structure, and performance, and the only difference is the rating marking on the label.



DIMENSIONS





RECOMMENDED PAD DIMENSIONS



Please refer to the performance below for the temperature

conditions of soldering.

STANDARD TEST BODY



Glass epoxy body on one side Board thickness 1.6mm Copper layer 70µm

I²t - t CHARACTERISTICS (REFERENCE DATA)





Code	Parts	Material
а	Fuse frame	Copper
b	Tiebar	Copper
с	Terminal	Copper foil, copper / nickel / tin plating
d	Exterior	Glass epoxy
е	Space	-

APPLICATION CLASSIFICATION BY USE

The application classification by use which divided the market and use into four is set up supposing our products being used for a broad use.

Please confirm the application classification by use of each product that you intend to use.

Moreover, please be sure to inform to our Sales Department in advance in examination of the use of those other than the indicated use.

Markat	Application	Use		Recommendation Type
by use	by use	Outline	Typical example of application	Circuit Protection Components
High reliability apparatus	1	 Apparatus in which advanced safety and reliability are demanded. Whether failure of the apparatus which cannot maintenance exchange products, and a product is direct for a human life, apparatus which changes or may cause a fatal system failure. 	- Space development apparatus relation (Satellite, Rocket, Artificial Satellite) - Aviation and a defensive system - Atomic power, fire power, and a water-power generation system	With no relevance
In-vehicle	2	 Apparatus in which reliability is important, The apparatus in which maintenance exchange of a product is very difficult, and failure of a product influence a human life, or the range of failure is wide range. 	 Vehicles control of transport machines, such as a car, and a railroad, a vessel [Engine control, drive control, brake control] The operation control system of the Shinkansen and a main artery 	Type KAB N series Type JAG N series Type KVA N series
Industrial apparatus	3	-Apparatus which can maintenance exchange products, and apparatus in which the loss of the system failure is large although failure of a product does not influence a human life, and maintenance engineering is demanded	 Vehicle indoor loading parts, such as an air-conditioner and car navigation, and in-vehicle communication facility Security management system for home/buildings etc. Control apparatus, such as Industrial use robots and a machine tool etc. 	Type KAB M series
Apparatus in general	4	 The small size and the thin article which applies leading-edge technology positively The product supposing being used widely in the market for the apparatus which can maintenance exchange products. and apparatus with a partial system failure by failure of product. 	-Smart phone. Mobile phone. Mobile PC (tablet), Electronic dictionary - Desktop PC, Notebook PC, Home network - Amusement apparatus (Pachinko,Game machine)	Туре КАВ Туре КАВ T series Туре КАВ Т Туре ЈАА Туре ЈАК Туре JAK Туре JAL Type JAK Туре JAC Туре JHC Туре КА

PERFORMANCE

Item	Performance	Test method
Temperature rise	Temperature rise shall not exceed 75°C.	Apply rated current.
Current-carrying capacity	Shall not open within 1 hour.	Apply rated current.
Clearing	Marking shall be legible. Shall not ignite, shall not explode the exterior	60VDC, 100A
Voltage drop	Type JAJ : 99mV, Type JAK : 83mV	Apply rated current.
	Fusing within 1 min.	Ambient temperature : 10 ~ 30°C
Fusing characteristics		Type JAJ : Apply 200% of rated current.
		Type JAK : Apply 250% of rated current.
Insulation resistance	1 MΩ or more	Insulation resistance between terminals and case
Electrode strength	No mechanical damage.	Board supporting width : 90 mm Bending : 3 mm
(Bending)	Resistance change alter the test shall be within $\pm 20\%$.	Bending speed : Approx. 0.5 mm/sec. Duration : 60±5 sec.
Electrode strength	There is no peeling between the terminal and the substrate.	Applied force : 17.7 N
(Shear test)	Resistance change after the test shall be within \pm 20%.	Tool : R0.5
		Pressurize from the side of the product
	No mechanical damage.	Supporting dimension : 1.6 mm
Substrate bending	Resistance change after the test shall be within \pm 20%.	Duration : 10 sec.
test		Tool : R0.5 Direction of the process thickness direction of product
	Solder Wetting time : within 3sec	Solder : Sn-3Aa-0.5Cu
	Solder Wetting time . Within 5sec.	Temperature : 245±3°C
Solderability		meniscograph method
(Solder Wetting time)		Solder : JISZ3282 H60A,H60S,H63A Temperature : 230±2°C
		meniscograph method
	The dipping surface of the terminals shall be covered more than	Solder : Sn-3Ag-0.5Cu
Solderability	95% with new solder.	Dipping : 3 sec.
(new uniform coating of		Solder : JISZ3282 H60A,H60S,H63A
solder)		Temperature : 230±2°C
	Marking shall be legible	Measure after 1 hour left under room temperature and humidity
	No mechanical damage.	After soldering, leave it in normal temperature and humidity for 1 hour or more,
	Resistance change after the test shall be within \pm 20%.	and measure the resistance value.
		<soldering conditions=""></soldering>
		Dipping (1 cycle)
Resistance to		Temperature : $265\pm3^{\circ}C/6\sim7s$.
soldering heat		Reflow soldering (2 cycles)
		Preconditioning : 1~2min 180°C or less Peak : may 250+5°C 5s
		Holding : 230~250°C 30~40s
		Cooling : more than 2min
		Temperature : 350±10°C
		Duration : 3~4s
Vibration	No mechanical damage.	Vibration amplitude $\stackrel{:}{_{\cdot}}$ 5G (49m/s^2) , $$ Vibration time $\stackrel{:}{_{\cdot}}$ 20min
	Resistance change after the test shall be within \pm 20%.	Frequency range : 10~2000Hz
	No mechanical damage	Number of cycles: 12 cycles each in 3 directions of XYZ (36 in total)
Shock	Resistance change after the test shall be within $\pm 20\%$.	Peak acceleration : 1500G (14700m/s ²)
		6 sides x 3 times (18 times in total)
Temperature cycle	No mechanical damage.	Perform 10 cycles with steps 1 and 2 below as one cycle. The transition time
Tomporatare eyolo	Resistance change after the test shall be within \pm 20%.	between stage 1 and stage 2 shall be within 3 min.
		Step1:-55°C±3°C/30±3min
		Step2 : 125±2°C/30±3min
	No mechanical damage.	Temperature : 85±3°C
Moisture resistance	Resistance change after the test shall be within \pm 20%.	Humidity : 85±5%RH
	N No mechanical damage.	Temperature : 85±2°C
Load life	Resistance change after the test shall be within \pm 20%.	Current : rated current \times 70%
		Duration : 1000 h
Moisture resistance	No mechanical damage.	Temperature : 85±3°C Humidity : 85±5%RH
load	Resistance change after the test shall be within $\pm 20\%$.	Current : rated current \times 70%
		Duration : 1000 h
High temperature	No mechanical damage.	Temperature : 125±2°C
exposure	Resistance change after the test shall be within \pm 20%.	Duration : 1000 h
(Stability)		Dissing since
Solvent resistance	Marking shall be legible.	Solvent : Isopropyl alcohol
	No damage to the appearance.	Duration : 90 sec.
	resistance value before the test	

Application Notes for Micro Fuse

1. Circuit Design

Micro Fuse should be designated only after confirming operating conditions and Micro Fuse performance characteristics.

When determining the rated current, be sure to observe the following items :

- (1) Micro Fuse should always be operated below the rated current (the value considered in the temperature derating rate) and voltage specifications.
- (2) Micro Fuse should always be operated below the rated voltage.
- (3) Micro Fuse should be selected with correct rated value to be fused at overload current.
- (4) When Micro Fuse are used in inrush current applications, please confirm sufficiently inrush resistance of Micro Fuse.
- (5) Please do not apply the current exceeding the breaking current to Micro Fuse.
- (6) Use Micro Fuse under the condition of category temperature.
- (7) Micro Fuse should not be used in the primary power source.

Micro Fuse should be selected by determining the operating conditions that will occur after final assembly, or estimating potential abnormalities through cycle testing.

2. Assembly and Mounting

During the entire assembly process, observe Micro Fuse body temperature and the heating time specified in the performance table. In addition, observe the following items

- (1) Mounting and adjusting with soldering irons are not recommended since temperature and time control is difficult.
- In case of emergency for using soldering irons, be sure to observe the conditions specified in the performance table.
- (2) Micro Fuse body should not contact a soldering iron directly.
- (3) Once Micro Fuse mounted on the board, they should never be remounted on boards or substrates.
- (4) During mounting, be careful not to apply any excessive mechanical stresses to the Micro Fuse.

3. Solvents

For cleaning of Micro Fuse, immersion in isopropyl alcohol for 90 seconds (at 20 ~ 30°C liquid temp.) will not be damaged. If organic solvents will be used to Micro Fuse, be sure to preliminarily check that the solvent will not damage Micro Fuse .

4. Ultrasonic Cleaning

Ultrasonic cleaning is not recommended for Micro Fuse. This may cause damage to Micro Fuse such as broken terminals which results in electrical characteristics effects, etc. depending on the conditions.

If Ultrasonic cleaning process must be used, please evaluate the effects sufficiently before use.

5. Caution During Usage

- (1) Micro Fuse with electricity should never be touched. Micro Fuse with electricity may cause burning due to Micro Fuse high temperature. Also, in case of touching Micro Fuse without electricity, please check the safety temperature of Micro Fuse.
- (2) Protective eyeglasses should always be worn when performing fusing tests. However, there is a fear that Micro Fuse will explode during test. During fusing tests, please cover particles not to fly outward from the board or testing fixture. Caution is necessary during usage at all times.

6. Environmental Conditions

- (1) Micro Fuse should not be stored or operated in the presence of acids, or alkalis, or corrosive atmosphere.
- (2) Micro Fuse should not be vibrated, shocked, or pressed excessively.
- (3) Micro Fuse should not be operated in a flammable or explosive atmosphere.
- (4) Please do not use Micro fuse in the environment where dew condensation occurs.

In case Micro fuse has to be used under the dew condensation condition, please apply moisture-proof coating over Micro fuse. Covering Micro fuse with moisture-proof coating may affect electrical characteristics, please evaluate the effects sufficiently before use.

7. Emergency

In case of fire, smoking, or offensive odor during operation, please cut off the power in the circuit or pull the plug out.

8. Storage

- (1) Micro Fuse should not be stored in an environment with high temperature, low temperature, high humidity, condensation and dust and avoid direct sunlight or corrosive atmosphere such as H₂S(hydrogen sulfide) or SO₂(sulfur dioxide). Direct sunlight may cause decolorization and deformation of the exterior and taping. Also, solderability will be remarkably lower in high humidity.
- (2) If the products are stored for an extended period of time, please contact Matsuo Sales Department for recommendation. The longer storage term causes packages and tapings to worsen. If the products will be stored for longer term, please contact us for advice.
- (3) The products in taping, package, or box should not be given any kind of physical pressure. Deformation of taping or package may affect automatic mounting.

9. Disposal

When Micro Fuse are disposed of as waste or "scrap", they should be treated as "industrial waste". Micro Fuse contain various kinds of metals and resins.

10. Samples

Micro Fuse received as samples should not be used in any products or devices in the market. Samples are provided for a particular purpose such as configuration, confirmation of electrical characteristics, etc.



MATSUO ELECTRIC CO., LTD.

Please feel free to ask our Sales Department for more information on Micro Fuse.

Head office URL

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